# bq4010/bq4010Y

## 8Kx8 Nonvolatile SRAM

## Features

- Data retention in the absence of power
- Automatic write-protection during power-up/power-down cycles
- Industry-standard 28-pin 8K x 8 pinout
- Conventional SRAM operation; unlimited write cycles
- 10-year minimum data retention in absence of power
- Battery internally isolated until power is applied

## General Description

The CMOS bq4010 is a nonvolatile 65,536-bit static RAM organized as 8,192 words by 8 bits. The integral control circuitry and lithium energy source provide reliable nonvolatility coupled with the unlimited write cycles of standard SRAM.

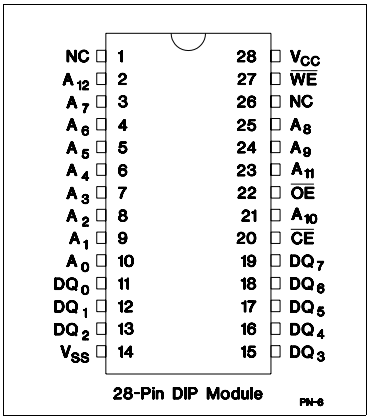
The control circuitry constantly monitors the single 5V supply for an out-of-tolerance condition. When $V_{CC}$ falls out of tolerance, the SRAM is unconditionally write-protected to prevent inadvertent write operation.

At this time the integral energy source is switched on to sustain the memory until after $V_{CC}$ returns valid.

The bq4010 uses an extremely low standby current CMOS SRAM, coupled with a small lithium coin cell to provide nonvolatility without long write-cycle times and the write-cycle limitations associated with EEPROM.

The bq4010 requires no external circuitry and is socket-compatible with industry-standard SRAMs and most EPROMs and EEPROMs.

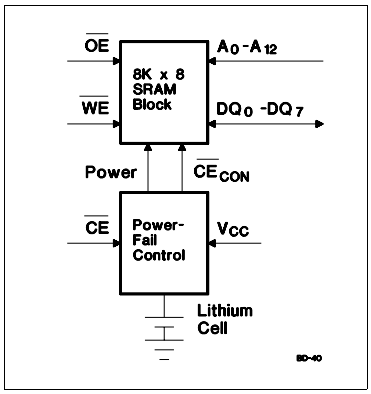
## Pin Connections




## Pin Names

| | |
|---|---|
| $A_0$ –$A_{12}$ | Address inputs |
| $DQ_0$–$DQ_7$ | Data input/output |
| $\overline{CE}$ | Chip enable input |
| $\overline{OE}$ | Output enable input |
| $\overline{WE}$ | Write enable input |
| NC | No connect |
| $V_{CC}$ | +5 volt supply input |
| $V_{SS}$ | Ground |

## Block Diagram




## Selection Guide

| Part Number | Maximum Access Time (ns) | Negative Supply Tolerance | Part Number | Maximum Access Time (ns) | Negative Supply Tolerance |
|---|---|---|---|---|---|
| | | | bq4010Y -70 | 70 | -10% |
| bq4010 -85 | 85 | -5% | bq4010Y -85 | 85 | -10% |
| bq4010 -150 | 150 | -5% | bq4010Y -150 | 150 | -10% |
| bq4010 -200 | 200 | -5% | bq4010Y -200 | 200 | -10% |

Sept. 1996 D

# Functional Description

When power is valid, the bq4010 operates as a standard CMOS SRAM. During power-down and power-up cycles, the bq4010 acts as a nonvolatile memory, automatically protecting and preserving the memory contents.

Power-down/power-up control circuitry constantly monitors the $V_{CC}$ supply for a power-fail-detect threshold $V_{PFD}$. The bq4010 monitors for $V_{PFD}$ = 4.62V typical for use in systems with 5% supply tolerance. The bq4010Y monitors for $V_{PFD}$ = 4.37V typical for use in systems with 10% supply tolerance.

When $V_{CC}$ falls below the $V_{PFD}$ threshold, the SRAM automatically write-protects the data. All outputs become high impedance, and all inputs are treated as "don't care." If a valid access is in process at the time of power-fail detection, the memory cycle continues to completion. If the memory cycle fails to terminate within time $t_{WPT}$, write-protection takes place.

As $V_{CC}$ falls past $V_{PFD}$ and approaches 3V, the control circuitry switches to the internal lithium backup supply, which provides data retention until valid $V_{CC}$ is applied.

When $V_{CC}$ returns to a level above the internal backup cell voltage, the supply is switched back to $V_{CC}$. After $V_{CC}$ ramps above the $V_{PFD}$ threshold, write-protection continues for a time $t_{CER}$ (120ms maximum) to allow for processor stabilization. Normal memory operation may resume after this time.

The internal coin cell used by the bq4010 has an extremely long shelf life and provides data retention for more than 10 years in the absence of system power.

As shipped from Benchmarq, the integral lithium cell is electrically isolated from the memory. (Self-discharge in this condition is approximately 0.5% per year.) Following the first application of $V_{CC}$, this isolation is broken, and the lithium backup cell provides data retention on subsequent power-downs.

## Truth Table

| Mode | $\overline{CE}$ | $\overline{WE}$ | $\overline{OE}$ | I/O Operation | Power |
|---|---|---|---|---|---|
| Not selected | H | X | X | High Z | Standby |
| Output disable | L | H | H | High Z | Active |
| Read | L | H | L | $D_{OUT}$ | Active |
| Write | L | L | X | $D_{IN}$ | Active |

## Absolute Maximum Ratings

| Symbol | Parameter | Value | Unit | Conditions |
|---|---|---|---|---|
| $V_{CC}$ | DC voltage applied on $V_{CC}$ relative to $V_{SS}$ | -0.3 to 7.0 | V | |
| $V_T$ | DC voltage applied on any pin excluding $V_{CC}$ relative to $V_{SS}$ | -0.3 to 7.0 | V | $V_T \le V_{CC} + 0.3$ |
| $T_{OPR}$ | Operating temperature | 0 to +70 | °C | Commercial |
| | | -40 to +85 | °C | Industrial "N" |
| $T_{STG}$ | Storage temperature | -40 to +70 | °C | Commercial |
| | | -40 to +85 | °C | Industrial "N" |
| $T_{BIAS}$ | Temperature under bias | -10 to +70 | °C | Commercial |
| | | -40 to +85 | °C | Industrial "N" |
| $T_{SOLDER}$ | Soldering temperature | +260 | °C | For 10 seconds |

**Note:** Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

## Recommended DC Operating Conditions ($T_A = T_{OPR}$)

| Symbol | Parameter | Minimum | Typical | Maximum | Unit | Notes |
|---|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage | 4.5 | 5.0 | 5.5 | V | bq4010Y/bq4010Y-xxxN |
| | | 4.75 | 5.0 | 5.5 | V | bq4010 |
| $V_{SS}$ | Supply voltage | 0 | 0 | 0 | V | |
| $V_{IL}$ | Input low voltage | -0.3 | - | 0.8 | V | |
| $V_{IH}$ | Input high voltage | 2.2 | - | $V_{CC}$ + 0.3 | V | |

**Note:** Typical values indicate operation at $T_A$ = 25°C.

## DC Electrical Characteristics ($T_A = T_{OPR}$, $V_{CCmin} \leq V_{CC} \leq V_{CCmax}$)

| Symbol | Parameter | Minimum | Typical | Maximum | Unit | Conditions/Notes |
|---|---|---|---|---|---|---|
| $I_{LI}$ | Input leakage current | - | - | ± 1 | µA | $V_{IN} = V_{SS}$ to $V_{CC}$ |
| $I_{LO}$ | Output leakage current | - | - | ± 1 | µA | $\overline{CE} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$ |
| $V_{OH}$ | Output high voltage | 2.4 | - | - | V | $I_{OH}$ = -1.0 mA |
| $V_{OL}$ | Output low voltage | - | - | 0.4 | V | $I_{OL}$ = 2.1 mA |
| $I_{SB1}$ | Standby supply current | - | 4 | 7 | mA | $\overline{CE} = V_{IH}$ |
| $I_{SB2}$ | Standby supply current | - | 2.5 | 4 | mA | $\overline{CE} \geq V_{CC}$ - 0.2V, $0V \leq V_{IN} \leq 0.2V$, or $V_{IN} \geq V_{CC}$ - 0.2V |
| $I_{CC}$ | Operating supply current | - | 65 | 75 | mA | Min. cycle, duty = 100%, $\overline{CE} = V_{IL}$, $I_{I/O}$ = 0mA |
| $V_{PFD}$ | Power-fail-detect voltage | 4.55 | 4.62 | 4.75 | V | bq4010 |
| | | 4.30 | 4.37 | 4.50 | V | bq4010Y |
| $V_{SO}$ | Supply switch-over voltage | - | 3 | - | V | |

**Note:** Typical values indicate operation at $T_A$ = 25°C, $V_{CC}$ = 5V.

## Capacitance ($T_A$ = 25°C, F = 1MHz, $V_{CC}$ = 5.0V)

| Symbol | Parameter | Minimum | Typical | Maximum | Unit | Conditions |
|---|---|---|---|---|---|---|
| $C_{I/O}$ | Input/output capacitance | - | - | 10 | pF | Output voltage = 0V |
| $C_{IN}$ | Input capacitance | - | - | 10 | pF | Input voltage = 0V |

**Note:** These parameters are sampled and not 100% tested.

## AC Test Conditions

| Parameter | Test Conditions |
|---|---|
| Input pulse levels | 0V to 3.0V |
| Input rise and fall times | 5 ns |
| Input and output timing reference levels | 1.5 V (unless otherwise specified) |
| Output load (including scope and jig) | See Figures 1 and 2 |

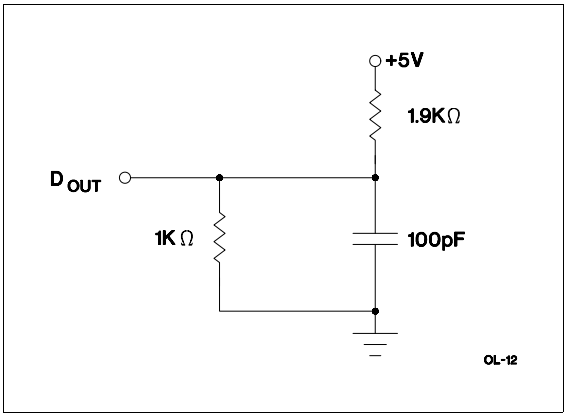



**Figure 1. Output Load A**

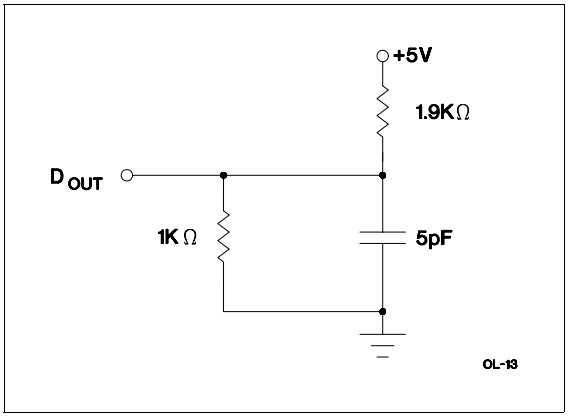
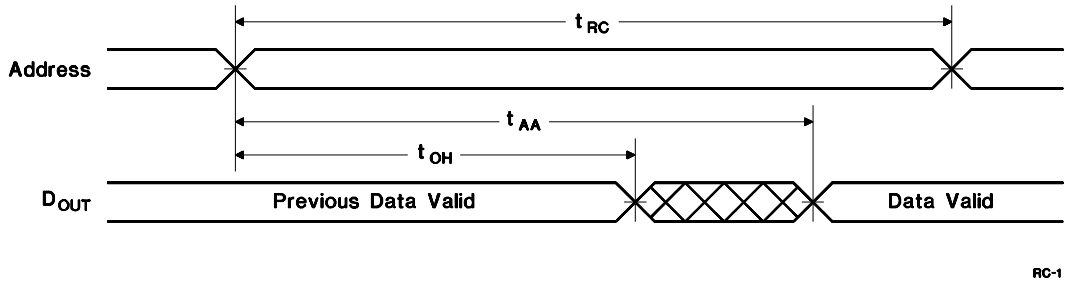



**Figure 2. Output Load B**

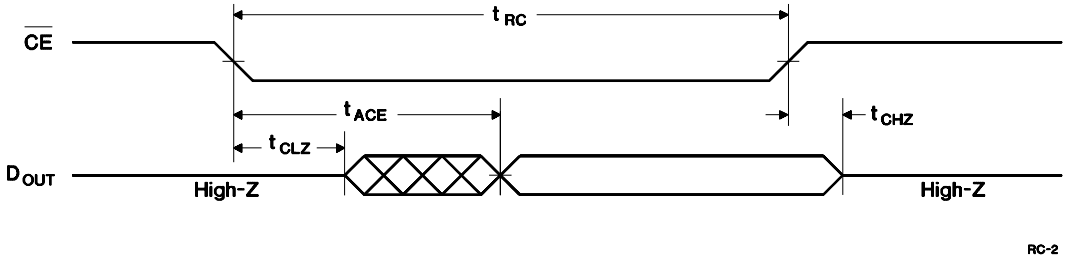
## Read Cycle ($T_A = T_{OPR}$, $V_{CCmin} \leq V_{CC} \leq V_{CCmax}$)

| Symbol | Parameter | -70/-70N | | -85/-85N | | -150/-150N | | -200 | | Unit | Conditions |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | | |
| $t_{RC}$ | Read cycle time | 70 | - | 85 | - | 150 | - | 200 | - | ns | |
| $t_{AA}$ | Address access time | - | 70 | - | 85 | - | 150 | - | 200 | ns | Output load A |
| $t_{ACE}$ | Chip enable access time | - | 70 | - | 85 | - | 150 | - | 200 | ns | Output load A |
| $t_{OE}$ | Output enable to output valid | - | 35 | - | 45 | - | 70 | - | 90 | ns | Output load A |
| $t_{CLZ}$ | Chip enable to output in low Z | 5 | - | 5 | - | 10 | - | 10 | - | ns | Output load B |
| $t_{OLZ}$ | Output enable to output in low Z | 5 | - | 5 | - | 5 | - | 5 | - | ns | Output load B |
| $t_{CHZ}$ | Chip disable to output in high Z | 0 | 25 | 0 | 40 | 0 | 60 | 0 | 70 | ns | Output load B |
| $t_{OHZ}$ | Output disable to output in high Z | 0 | 25 | 0 | 30 | 0 | 50 | 0 | 70 | ns | Output load B |
| $t_{OH}$ | Output hold from address change | 10 | - | 10 | - | 10 | - | 10 | - | ns | Output load A |

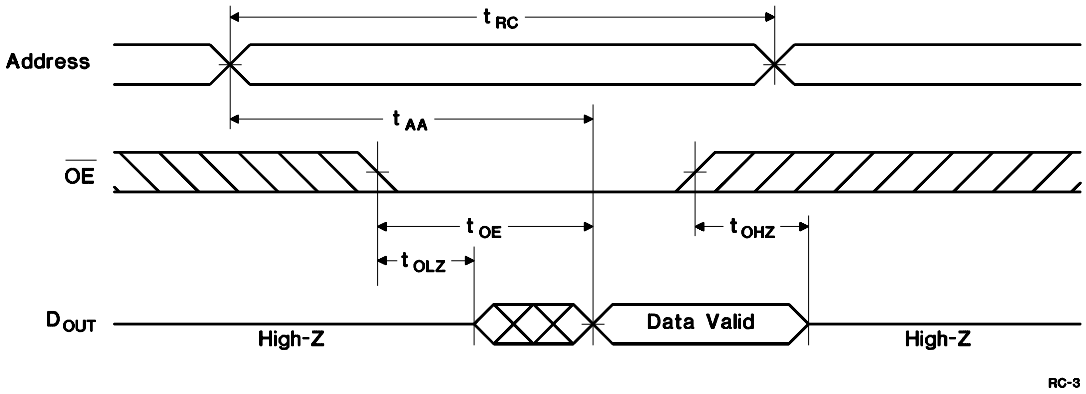
## Read Cycle No. 1 (Address Access) [1,2]




## Read Cycle No. 2 ($\overline{CE}$ Access) [1,3,4]




## Read Cycle No. 3 ($\overline{OE}$ Access) [1,5]




**Notes:**
1. $\overline{WE}$ is held high for a read cycle.
2. Device is continuously selected: $\overline{CE}$ = $\overline{OE}$ = $V_{IL}$.
3. Address is valid prior to or coincident with $\overline{CE}$ transition low.
4. $\overline{OE}$ = $V_{IL}$.
5. Device is continuously selected: $\overline{CE}$ = $V_{IL}$.

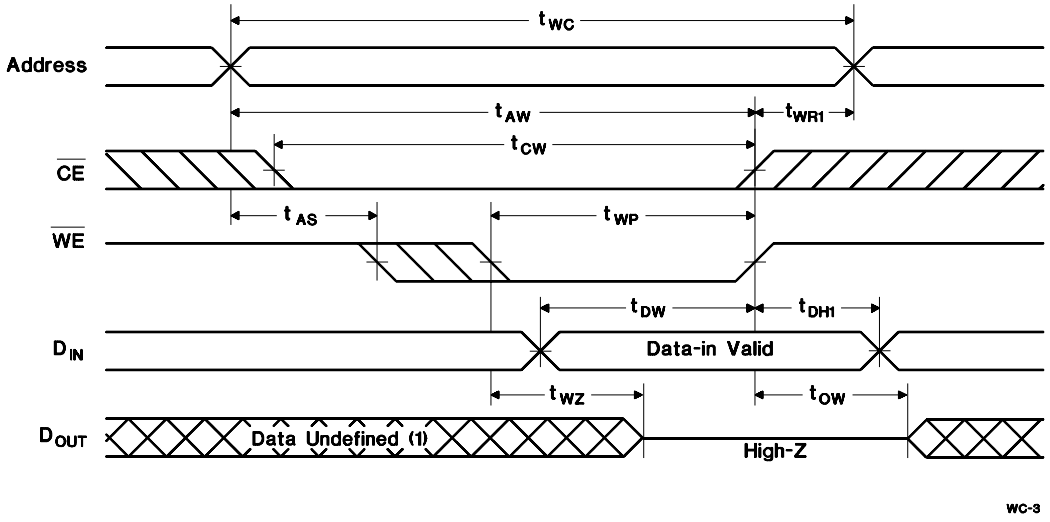
## Write Cycle ($T_A = T_{OPR}$, $V_{CCmin} \leq V_{CC} \leq V_{CCmax}$)

| Symbol | Parameter | -70/-70N | | -85/-85N | | -150/-150N | | -200 | | Units | Conditions/Notes |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | | |
| $t_{WC}$ | Write cycle time | 70 | - | 85 | - | 150 | - | 200 | - | ns | |
| $t_{CW}$ | Chip enable to end of write | 55 | - | 75 | - | 100 | - | 150 | - | ns | (1) |
| $t_{AW}$ | Address valid to end of write | 55 | - | 75 | - | 90 | - | 150 | - | ns | (1) |
| $t_{AS}$ | Address setup time | 0 | - | 0 | - | 0 | - | 0 | - | ns | Measured from address valid to beginning of write. (2) |
| $t_{WP}$ | Write pulse width | 55 | - | 65 | - | 90 | - | 130 | - | ns | Measured from beginning of write to end of write. (1) |
| $t_{WR1}$ | Write recovery time (write cycle 1) | 5 | - | 5 | - | 5 | - | 5 | - | ns | Measured from $\overline{WE}$ going high to end of write cycle. (3) |
| $t_{WR2}$ | Write recovery time (write cycle 2) | 15 | - | 15 | - | 15 | - | 15 | - | ns | Measured from $\overline{CE}$ going high to end of write cycle. (3) |
| $t_{DW}$ | Data valid to end of write | 30 | - | 35 | - | 50 | - | 70 | - | ns | Measured from first low-to-high transition of either $\overline{CE}$ or $\overline{WE}$. |
| $t_{DH1}$ | Data hold time (write cycle 1) | 0 | - | 0 | - | 0 | - | 0 | - | ns | Measured from $\overline{WE}$ going high to end of write cycle. (4) |
| $t_{DH2}$ | Data hold time (write cycle 2) | 10 | - | 10 | - | 0 | - | 0 | - | ns | Measured from $\overline{CE}$ going high to end of write cycle. (4) |
| $t_{WZ}$ | Write enabled to output in high Z | 0 | 25 | 0 | 30 | 0 | 50 | 0 | 70 | ns | I/O pins are in output state. (5) |
| $t_{OW}$ | Output active from end of write | 5 | - | 5 | - | 5 | - | 5 | - | ns | I/O pins are in output state. (5) |

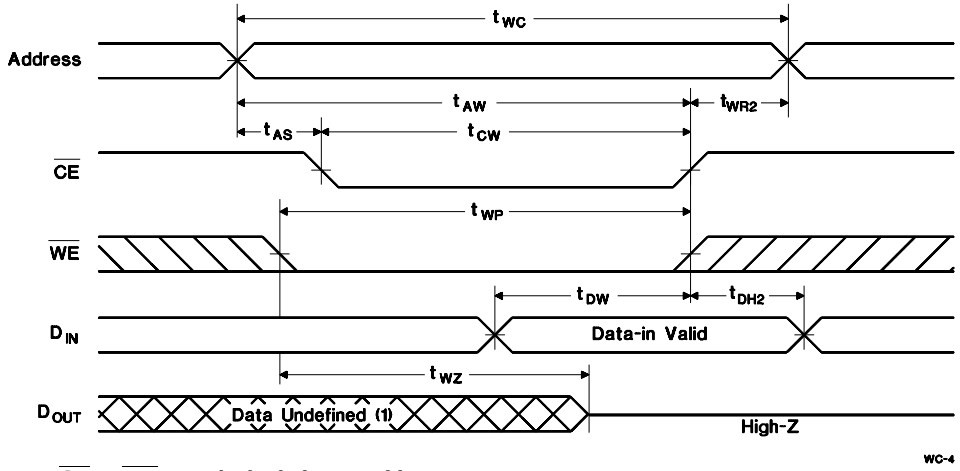
**Notes:**

1. A write ends at the earlier transition of $\overline{CE}$ going high and $\overline{WE}$ going high.
2. A write occurs during the overlap of a low $\overline{CE}$ and a low $\overline{WE}$. A write begins at the later transition of $\overline{CE}$ going low and $\overline{WE}$ going low.
3. Either $t_{WR1}$ or $t_{WR2}$ must be met.
4. Either $t_{DH1}$ or $t_{DH2}$ must be met.
5. If $\overline{CE}$ goes low simultaneously with $\overline{WE}$ going low or after $\overline{WE}$ going low, the outputs remain in high-impedance state.

## Write Cycle No. 1 ($\overline{WE}$-Controlled) [1,2,3]




## Write Cycle No. 2 ($\overline{CE}$-Controlled) [1,2,3,4,5]




**Notes:**

1. $\overline{CE}$ or $\overline{WE}$ must be high during address transition.
2. Because I/O may be active ($\overline{OE}$ low) during this period, data input signals of opposite polarity to the outputs must not be applied.
3. If $\overline{OE}$ is high, the I/O pins remain in a state of high impedance.
4. Either $t_{WR1}$ or $t_{WR2}$ must be met.
5. Either $t_{DH1}$ or $t_{DH2}$ must be met.

## Power-Down/Power-Up Cycle ($T_A = T_{OPR}$)

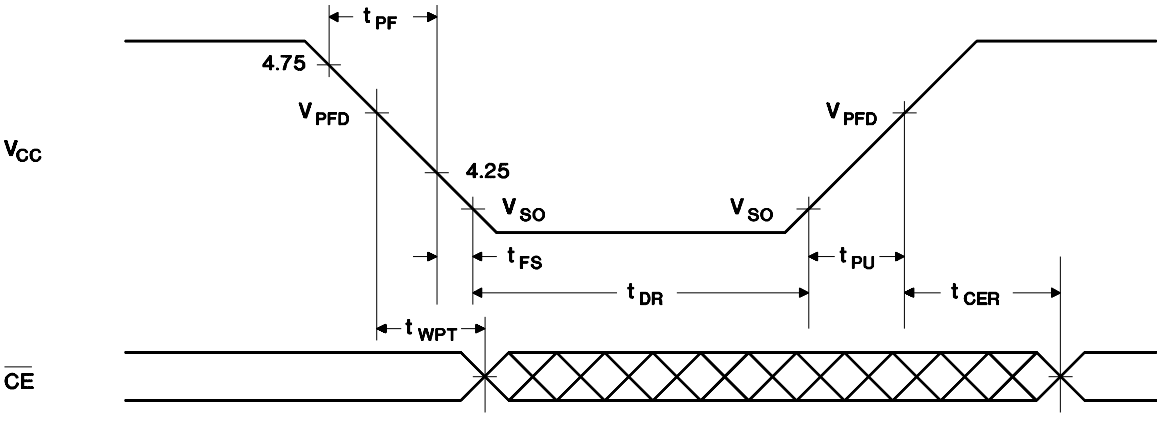
| Symbol | Parameter | Min. | Typ. | Max. | Unit | Conditions |
|---|---|---|---|---|---|---|
| $t_{PF}$ | $V_{CC}$ slew, 4.75 to 4.25 V | 300 | - | - | µs | |
| $t_{FS}$ | $V_{CC}$ slew, 4.25 to $V_{SO}$ | 10 | - | - | µs | |
| $t_{PU}$ | $V_{CC}$ slew, $V_{SO}$ to $V_{PFD}$ (max.) | 0 | - | - | µs | |
| $t_{CER}$ | Chip enable recovery time | 40 | 80 | 120 | ms | Time during which SRAM is write-protected after $V_{CC}$ passes $V_{PFD}$ on power-up. |
| $t_{DR}$ | Data-retention time in absence of $V_{CC}$ | 10 | - | - | years | $T_A$ = 25°C. (2) |
| $t_{DR-N}$ | Data-retention time in absence of $V_{CC}$ | 6 | - | - | years | $T_A$ = 25°C (2); industrial temperature range (-N) only. |
| $t_{WPT}$ | Write-protect time | 40 | 100 | 150 | µs | Delay after $V_{CC}$ slews down past $V_{PFD}$ before SRAM is write-protected. |

**Notes:** 1. Typical values indicate operation at $T_A$ = 25°C, $V_{CC}$ = 5V.

2. Battery is disconnected from circuit until after $V_{CC}$ is applied for the first time. $t_{DR}$ is the accumulated time in absence of power beginning when power is first applied to the device.

**Caution: Negative undershoots below the absolute maximum rating of -0.3V in battery-backup mode may affect data integrity.**

## Power-Down/Power-Up Timing



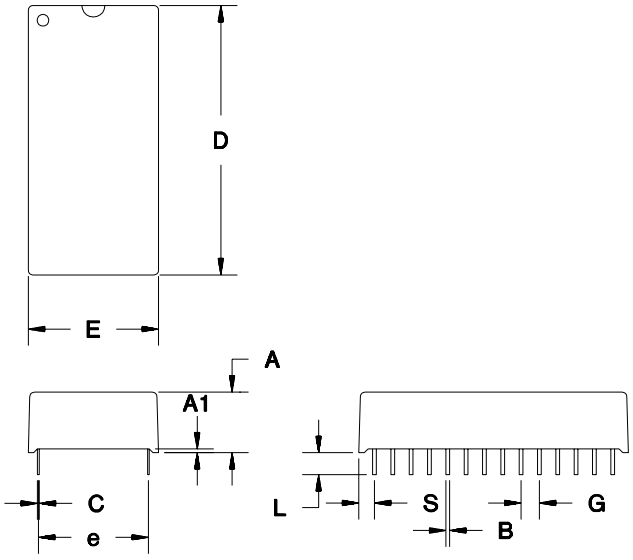

PD-B

## Data Sheet Revision History

| Change No. | Page No. | Description |
|---|---|---|
| 1 | 2, 3, 4, 6, 8, 9 | Added industrial temperature range for bq4010YMA-85N and -150N. |
| 2 | 1, 4, 6, 9 | Added 70 ns speed grade for bq4010-70 and bq4010Y-70 and added industrial temperature range for bq4010YMA-70N. |
| 3 | 1 | Removed 70ns speed grade for bq4010-70. |

**Notes:** Change 1 = Sept 1991 B changes from Sept. 1990 A.
Change 2 = Feb. 1994 C changes from Sept. 1991 B.
Change 3 = Sept. 1996 D changes from Feb. 1994 C.

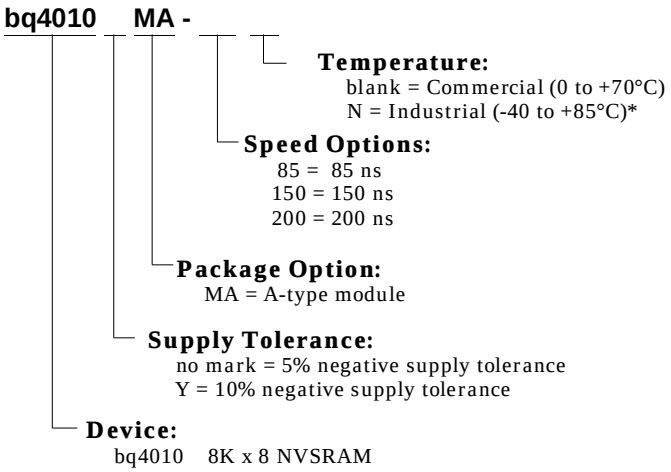
## MA: 28-Pin A-Type Module




### 28-Pin MA (A-Type Module)

| Dimension | Inches | | Millimeters | |
|---|---|---|---|---|
| | Min. | Max. | Min. | Max. |
| A | 0.365 | 0.375 | 9.27 | 9.53 |
| A1 | 0.015 | - | 0.38 | - |
| B | 0.017 | 0.023 | 0.43 | 0.58 |
| C | 0.008 | 0.013 | 0.20 | 0.33 |
| D | 1.470 | 1.500 | 37.34 | 38.10 |
| E | 0.710 | 0.740 | 18.03 | 18.80 |
| e | 0.590 | 0.630 | 14.99 | 16.00 |
| G | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.120 | 0.150 | 3.05 | 3.81 |
| S | 0.075 | 0.110 | 1.91 | 2.79 |

## Ordering Information




***Note:** Only 10% supply ("Y") version is available in industrial temperature range; contact factory for speed grade availability.

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